

IN THE CLAIMS:

Please add claims 28-40, as follows:

28. A method of constructing a multi-chip package, comprising:

electrically connecting a semiconductor die to at least one of a plurality of shelves;

electrically connecting a flip-chip to a ceramic substrate; and

attaching said ceramic substrate to one of said plurality of shelves.

29. The method of claim 28, further comprising electrically connecting said ceramic substrate to at least one of said plurality of shelves.

30. The method of claim 29, wherein electrically connecting said ceramic substrate to at least one of said plurality of shelves comprises electrically connecting said ceramic substrate to at least one of said plurality of shelves with at least one bond wire.

31. The method of claim 28, wherein attaching said ceramic substrate to one of said plurality of shelves provides a lid above said semiconductor die.

32. The method of claim 28, further comprising electrically testing said electrically connected flip-chip before attaching of said ceramic substrate to said one of said plurality of shelves.

33. The method of claim 28, wherein electrically connecting said flip-chip to said ceramic substrate comprises electrically connecting said flip-chip to said ceramic substrate with solder balls.

34. The method of claim 28, further comprising covering said flip-chip with an encapsulant.

35. The method of claim 28, further comprising disposing a seal between a base of said ceramic substrate and one of said plurality of shelves to which said ceramic substrate is attached.

36. The method of claim 28, wherein electrically connecting said semiconductor die to said at least one of a plurality of shelves comprises electrically connecting a CPU chip to said at least one of said plurality of shelves.

37. The method of claim 28, wherein electrically connecting said flip-chip to said ceramic substrate comprises electrically connecting a memory cache flip-chip to said ceramic substrate.

38. The method of claim 28, wherein electrically connecting said semiconductor die to at least one of said plurality of shelves comprises electrically connecting said semiconductor die to said at least one of a plurality of shelves with at least one bond wire.

39. The method of claim 28, further including attaching said semiconductor die to a slug.

40. The method of claim 39, further comprising attaching said slug to at least one of a plurality of shelves.

Please cancel claims 28-37, without prejudice.